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Semiconductor devices with redistribution structures configured for switchable routing

Abstract

Semiconductor devices having redistribution structures, and associated systems and methods, are disclosed herein. In one embodiment, a semiconductor package includes a first semiconductor die including a first redistribution structure and a second semiconductor die including a second redistribution structure. The first and second semiconductor dies can be mounted on a package substrate such that the first and second redistribution structures are aligned with each other. In some embodiments, an interconnect structure can be positioned between the first and second semiconductor dies to electrically couple the first and second redistribution structures to each other. The first and second redistribution structures can be configured such that signal routing between the first and second semiconductor dies can be altered based on the location of the interconnect structure.

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Background/Summary

CROSS-REFERENCE TO RELATED APPLICATION(S) (1) This application is a continuation of U.S. application Ser. No. 17/521,173, filed Nov. 8, 2021, now U.S. Pat. No. 11,791,316; which is a continuation of U.S. application Ser. No. 16/836,283, filed Mar. 31, 2020, now U.S. Pat. No. 11,171,121; which are incorporated herein by reference in their entirety.

TECHNICAL FIELD

(1) The present technology generally relates to semiconductor devices, and more particularly relates to semiconductor devices having redistribution structures configured to accommodate different package designs.

BACKGROUND

(2) Packaged semiconductor dies, including memory chips, microprocessor chips, and imager chips, typically include a semiconductor die mounted on a substrate and encased in a protective covering. The semiconductor die can include functional features, such as memory cells, processor circuits, and imager devices, as well as bond pads electrically connected to the functional features. The bond pads can be electrically connected to terminals outside the protective covering to allow the semiconductor die to be connected to higher level circuitry.

(3) Market pressures continually drive semiconductor manufacturers to reduce the size of die packages to fit within the space constraints of electronic devices, while also driving them to increase the functional capacity of each package to meet operating parameters. One approach for increasing the processing power of a semiconductor package without substantially increasing the surface area covered by the package (the package's "footprint") is to vertically stack multiple semiconductor dies on top of one another in a single package. The dies in such vertically stacked packages can be electrically coupled to each other and/or to a substrate via wires, interconnects, or other conductive structures. However, conventional structures and techniques for interconnecting vertically stacked semiconductor dies may not be able to accommodate different semiconductor package designs.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

(1) Many aspects of the present technology can be better understood with reference to the following drawings. The components in the drawings are not necessarily to scale. Instead, emphasis is placed on illustrating clearly the principles of the present technology.

(2) FIG. 1 is a side cross-sectional view of a semiconductor package configured in accordance with embodiments of the present technology.

(3) FIGS. 2A and 2B are perspective views of a first redistribution structure and a second redistribution structure configured for use with different package designs in accordance with embodiments of the present technology.

(4) FIGS. 3A and 3B illustrate a first semiconductor die and a second semiconductor die,

respectively, configured in accordance with embodiments of the present technology.

(5) FIGS. 4A and 4B illustrate signal routing through the first and second semiconductor dies of FIGS. 3A and 3B, respectively, in a first package design configured in accordance with embodiments of the present technology.

(6) FIGS. 5A and 5B illustrate signal routing through the first and second semiconductor dies of FIGS. 3A and 3B, respectively, in a second package design configured in accordance with embodiments of the present technology.

(7) FIGS. 6A-6D illustrate signal routing through a package substrate configured in accordance with embodiments of the present technology.

(8) FIG. 7 is a schematic view of a system that includes a semiconductor device or package configured in accordance with embodiments of the present technology.

DETAILED DESCRIPTION

(9) Specific details of several embodiments of semiconductor devices, and associated systems and methods, are described below. A person skilled in the relevant art will recognize that suitable stages of the methods described herein can be performed at the wafer level or at the die level. Therefore, depending upon the context in which it is used, the term “substrate” can refer to a wafer-level substrate or to a singulated, die-level substrate. Furthermore, unless the context indicates otherwise, structures disclosed herein can be formed using conventional semiconductor-manufacturing techniques. Materials can be deposited, for example, using chemical vapor deposition, physical vapor deposition, atomic layer deposition, plating, electroless plating, spin coating, and/or other suitable techniques. Similarly, materials can be removed, for example, using plasma etching, wet etching, chemical-mechanical planarization, or other suitable techniques.

(10) In several of the embodiments described below, a semiconductor package configured in accordance with the present technology includes a first semiconductor die including a first redistribution structure and a second semiconductor die including a second redistribution structure. The first and second semiconductor dies can be mounted on a substrate in a face-to-face (F2F) configuration such that at least some components of the first redistribution structure are aligned with corresponding components of the second redistribution structure. The semiconductor package can further include at least one interconnect structure (e.g., a solder bump) between the first and second redistribution structures to electrically couple the first and second semiconductor dies to each other.

(11) In some embodiments, the first and second redistribution structures are each configured to be compatible with multiple package designs (e.g., $\times 4$, $\times 8$, and/or $\times 16$ package designs). The location of the interconnect structure(s) can be used to switch or otherwise alter the routing of signals through the first and second redistribution structures to accommodate these different package designs. Accordingly, rather than requiring different redistribution structure designs for different packages, the present technology may allow the same redistribution structure designs to be used in different packages simply by varying the layout of the interconnect structures. The present technology can thus be desirable for reducing costs and supply chain complexity, and improving efficiency and flexibility of the design and manufacturing process.

(12) Numerous specific details are disclosed herein to provide a thorough and enabling description of embodiments of the present technology. A person skilled in the art, however, will understand that the technology may have additional embodiments and that the technology may be practiced without several of the details of the embodiments described below with reference to FIGS. 1-7. For example, some details of semiconductor devices and/or packages well known in the art have been omitted so as not to obscure the present technology. In general, it should be understood that various other devices and systems in addition to those specific embodiments disclosed herein may be within the scope of the present technology.

(13) As used herein, the terms “vertical,” “lateral,” “upper,” “lower,” “above,” and “below” can refer to relative directions or positions of features in the semiconductor devices in view of the

orientation shown in the Figures. For example, “upper” or “uppermost” can refer to a feature positioned closer to the top of a page than another feature. These terms, however, should be construed broadly to include semiconductor devices having other orientations, such as inverted or inclined orientations where top/bottom, over/under, above/below, up/down, and left/right can be interchanged depending on the orientation.

(14) FIG. 1 is a side cross-sectional view of a semiconductor package **100** (“package **100**”) configured in accordance with embodiments of the present technology. The package **100** can include a first semiconductor die **102a** and a second semiconductor die **102b** disposed over a package substrate **103**. The first and second semiconductor dies **102a-b** can each include a respective semiconductor substrate **104a-b** (e.g., a silicon substrate, a gallium arsenide substrate, an organic laminate substrate, etc.) having a respective upper side or surface **106a-b** and a respective lower side or surface **108a-b**. In some embodiments, the first and second semiconductor dies **102a-b** are vertically arranged with the second semiconductor die **102b** mounted on the first semiconductor die **102a** such that the lower surface **108b** of the second semiconductor die **102b** faces the upper surface **106a** of the first semiconductor die **102a**. The first semiconductor die **102a** can be mounted on the package substrate **103** such that the lower surface **108a** of the first semiconductor die **102a** faces and is coupled to the package substrate **103**.

(15) In some embodiments, at least one of the surfaces of each of the first and second semiconductor dies **102a-b** is an active surface including various types of semiconductor components, such as memory circuits, (e.g., dynamic random-access memory (DRAM), static random-access memory (SRAM), flash memory, or other type of memory circuits), controller circuits (e.g., DRAM controller circuits), logic circuits, processing circuits, circuit elements (e.g., wires, traces, interconnects, transistors, etc.), imaging components, and/or other semiconductor features. The first and second semiconductor dies **102a-b** can be mounted such that the active surfaces of the semiconductor dies **102a-b** face each other (e.g., a F2F configuration). For example, in the illustrated embodiment, the upper surface **106a** of the first semiconductor die **102a** and the lower surface **108b** of the second semiconductor die **102b** are active surfaces.

(16) The first and second semiconductor dies **102a-b** can be coupled (e.g., mechanically, thermally, and/or electrically) to each other by at least one interconnect structure **109** (e.g., bumps, micro-bumps, pillars, columns, studs, etc.—a single interconnect structure is shown in FIG. 1 merely for purposes of clarity). Each interconnect structure **109** can be formed of any suitably conductive material such as copper, nickel, gold, silicon, tungsten, solder (e.g., SnAg-based solder), conductive-epoxy, combinations thereof, etc., and can be formed by electroplating, electroless-plating, or another suitable process. In some embodiments, the interconnect structure **109** can also include barrier materials (e.g., nickel, nickel-based intermetallic, and/or gold) formed over end portions of the interconnect structure **109**. The barrier materials can facilitate bonding and/or prevent or at least inhibit the electromigration of copper or other metals used to form the interconnect structure **109**. Optionally, the interconnect structure **109** can be surrounded by an underfill material (not shown).

(17) The package substrate **103** can be or include an interposer, such as a printed circuit board, a dielectric spacer, another semiconductor die (e.g., a logic die), or another suitable substrate. In some embodiments, the package substrate **103** includes additional semiconductor components (e.g., doped silicon wafers or gallium arsenide wafers), nonconductive components (e.g., various ceramic substrates, such as aluminum oxide (Al₂O₃), etc.), aluminum nitride, and/or conductive portions (e.g., interconnecting circuitry, through-silicon vias (TSVs), etc.). The package substrate **103** can further include electrical connectors **124** (e.g., solder balls, conductive bumps, conductive pillars, conductive epoxies, and/or other suitable electrically conductive elements) electrically coupled to the package substrate **103** and configured to electrically couple the package **100** to external devices or circuitry (not shown).

(18) The package **100** can further include a mold material **126** formed over the package substrate

103 and/or at least partially around the first and second semiconductor dies **102a-b**. The mold material **126** can be a resin, epoxy resin, silicone-based material, polyimide, or any other material suitable for encapsulating the first and second semiconductor dies **102a-b** and/or at least a portion of the package substrate **103** to protect these components from contaminants and/or physical damage. In some embodiments, the semiconductor package **100** includes other components such as external heatsinks, a casing (e.g., thermally conductive casing), electromagnetic interference (EMI) shielding components, etc.

(19) In some embodiments, the first and second semiconductor dies **102a-b** each include a respective redistribution layer or structure. For example, as shown in FIG. 1, the first semiconductor die **102a** includes a first redistribution structure **110a** formed on the upper surface **106a** and the second semiconductor die **102b** includes a second redistribution structure **110b** formed on the lower surface **108b**. The first and second redistribution structures **110a-b** can each include one or more electrically conductive components, such as contacts, traces, pads, pins, wiring, circuitry, and the like. The components of the redistribution structures **110a-b** can be made of any suitable conductive material, such as one or more metals (e.g., titanium, tungsten, cobalt, nickel, platinum, etc.), metal-containing compositions (e.g., metal silicide, metal nitride, metal carbide, etc.), and/or conductively-doped semiconductor materials (e.g., conductively-doped silicon, conductively-doped germanium, etc.). In some embodiments, the redistribution structures **110a-b** are or include an in-line redistribution layer (iRDL). An iRDL can be formed in a front-end phase of manufacturing process (e.g., prior to a wafer probe test).

(20) The first and second redistribution structures **110a-b** can be configured to electrically couple different portions of an individual semiconductor die to route signals therebetween. For example, the first redistribution structure **110a** can include a first signal trace **112a** extending between and electrically coupling a first die contact or pin **114a** and a package contact or pin **116**. The first die contact **114a** and the package contact **116** can be at different locations on the first semiconductor die **102a**. For example, the first die contact **114a** can be located at or near a central and/or interior portion of the first semiconductor die **102a**, while the package contact **116** can be located at or near a peripheral portion of the first semiconductor die **102a**. The package contact **116** can be electrically coupled to a corresponding bond pad **118** on the package substrate **103** via a conductive element such as a wire **120** (e.g., a wirebond). As a result, signals originating from the first semiconductor die **102a** can be transmitted to the package substrate **103** via the first redistribution structure **110a** (e.g., from the first die contact **114a** through the first signal trace **112a**, the package contact **116**, the wire **120**, and the bond pad **118** to the package substrate **103**).

(21) In the illustrated embodiment, the second semiconductor die **102b** does not have any package contacts for direct coupling to the substrate **103**. Instead, signals from the second semiconductor die **102b** can be routed to the package substrate **103** indirectly via the first semiconductor die **102a**, as described in greater detail below. In other embodiments, however, the second semiconductor die **102b** can include one or more package contacts configured to directly connect to the package substrate **103** (e.g., via wirebonds) to allow for direct signal transmission between the second semiconductor die **102b** and package substrate **103**. Optionally, some signals from the second semiconductor die **102b** can be transmitted to the package substrate **103** indirectly via the first semiconductor die **102a**, while other signals can be transmitted directly to the package substrate **103**.

(22) In the embodiment of FIG. 1, the first and second redistribution structures **110a-b** and interconnect structure **109** route signals from the second semiconductor die **102b** to the first semiconductor die **102a** and the package substrate **103**. The first signal trace **112a** of the first redistribution structure **110a** can be connected to a first interconnect pad **122a** (e.g., a bump pad). The first interconnect pad **122a** can be at or near the central and/or interior portion of the first semiconductor die **102a**, e.g., near the first die contact **114a**. In some embodiments, the first interconnect pad **122a** is located along the first signal trace **112a** between the first die contact **114a**

and the package contact **116**. The second redistribution structure **110b** can include a second signal trace **112b** extending between and electrically coupling a second die contact or pin **114b** and a second interconnect pad **122b** (e.g., a bump pad). The second die contact **114b** and the second interconnect pad **122b** can be located near each other, e.g., at or near the central and/or interior portion of the second semiconductor die **102b**.

(23) As shown in FIG. 1, when the first and second semiconductor dies **102a-b** are vertically arranged in a F2F configuration, the first and second redistribution structures **110a-b** can face each other such that the first and second interconnect pads **122a-b** are aligned. The first and second interconnect pads **122a-b** can be electrically coupled to each other via the interconnect structure **109**. As a result, signals originating from the second semiconductor die **102b** can be transmitted to the package substrate **103** via the first and second redistribution structures **110a-b** (e.g., from the second die contact **114b** through the second signal trace **112b**, the second interconnect pad **122b**, the interconnect structure **109**, the first interconnect pad **122a**, the first signal trace **112a**, the package contact **116**, the wire **120**, and the bond pad **118** to the package substrate **103**).

(24) In some embodiments, the first and second redistribution structures **110a-b** are configured to accommodate different types of semiconductor package designs. For example, the first and second redistribution structures **110a-b** can be used with at least two different package designs, such as a $\times 4/\times 8$ design and a $\times 16$ design. In some embodiments, a $\times 4/\times 8$ package provides **8** different data channels, while a $\times 16$ design provides **16** different data channels. The different package designs can involve different signal routing between the die contacts of the first semiconductor die **102a**, the die contacts of the second semiconductor die **102b**, and the package contacts of the first semiconductor die **102a**. In such embodiments, the signal routing between these components can be switched to a different configuration by changing the location(s) of the interconnect structure(s) **109** between the first and second redistribution structures **110a-b**, rather than by changing the design of the first and second redistribution structures **110a-b**.

(25) FIGS. 2A and 2B are perspective views of a first redistribution structure **200a** and a second redistribution structure **200b** configured for use with different package designs in accordance with embodiments of the present technology. The first and second redistribution structures **200a-b** can be incorporated in any of the embodiments described herein (e.g., as part of the first and second redistribution structures **110a-b** described with respect to FIG. 1). For example, the first redistribution structure **200a** can be formed on an upper surface of a first semiconductor die (e.g., a lower semiconductor die in a F2F semiconductor package—not shown) and the second redistribution structure **200b** can be formed on a lower surface of a second semiconductor die (e.g., an upper semiconductor die in a F2F semiconductor package—not shown). In other embodiments, this configuration can be reversed, such that the second redistribution structure **200b** is formed on the upper surface of the first semiconductor die and the first redistribution structure **200a** is formed on the lower surface of the second semiconductor die.

(26) Referring to FIGS. 2A and 2B together, the first redistribution structure **200a** includes a first signal trace **202** and a second signal trace **204**. The first signal trace **202** can electrically couple a first die contact **206**, a first interconnect pad **208**, and a first package contact **210**. The second signal trace **204** can electrically couple a second interconnect pad **212** to a second package contact **214**. In some embodiments, the first die contact **206** includes or is coupled to an output pin of the first semiconductor die (e.g., a data pin, an address pin, a control pin, etc.). The first interconnect pad **208** can be located along the first signal trace **202** between the first die contact **206** and the first package contact **210**. The first and second package contacts **210**, **214** can be configured to be electrically coupled to corresponding first and second bond pads of a package substrate (not shown) via wire-bonding or other techniques known to those of skill in the art. The first die contact **206**, first interconnect pad **208**, and second interconnect pad **212** can be located at a first portion of the first semiconductor die (e.g., a central and/or interior portion) and the first and second package contacts **210**, **214** can be located at a second, different portion of the first semiconductor die (e.g., a

peripheral portion). In some embodiments, the first and second signal traces **202**, **204** are spaced apart and/or electrically isolated from each other such that signals carried by the first signal trace **202** are not transmitted to the second signal trace **204**, and vice-versa.

(27) The second redistribution structure **200b** includes a third signal trace **216**. The third signal trace **216** can electrically couple a second die contact **218**, a third interconnect pad **220**, and fourth interconnect pad **222**. In some embodiments, the second die contact **218** includes or is coupled to an output pin of the second semiconductor die (e.g., a data pin, an address pin, a control pin, etc.). The third interconnect pad **220** can be located along the third signal trace **216** between the second die contact **218** and the fourth interconnect pad **222**. The second die contact **218**, third interconnect pad **220**, and fourth interconnect pad **222** can be located at a central and/or interior portion of the second semiconductor die. In some embodiments, the third signal trace **216** does not include any package contacts or other components that directly connect to a package substrate.

(28) When the first and second semiconductor dies are assembled in a F2F configuration, the first and second redistribution structures **200a-b** can be positioned near each other such that one or portions of the first and second redistribution structures **200a-b** are aligned and can be bridged by an interconnect structure **224**. For example, in the illustrated embodiment, the first interconnect pad **208** of the first redistribution structure **200a** is aligned with the third interconnect pad **220** of the second redistribution structure **200b**, such that the first interconnect pad **208** and third interconnect pad **220** can be electrically and mechanically coupled to each other by interconnect structure **224**. As can be seen in FIGS. 2A and 2B, the first interconnect pad **208** extends at least partially over the third interconnect pad **220** so that when viewed from directly above or below, the footprint of the first interconnect pad **208** at least partially overlaps the footprint of the third interconnect pad **220**. Optionally, the central vertical axis of the first interconnect pad **208** can be collinear with or at least partially overlap the central vertical axis of the third interconnect pad **220**. The second interconnect pad **212** of the first redistribution structure **200a** can be aligned with the fourth interconnect pad **222** of the second redistribution structure **200b** in a similar manner. In some embodiments, an interconnect structure **224** is used to electrically couple the first and second redistribution structures **200a-b** to each other. The positioning of the interconnect structure **224** can be selected to create a desired signal routing path between the first die contact **206**, second die contact **218**, first package contact **210**, and second package contact **214**.

(29) Referring to FIG. 2A, for example, in a first package design (e.g., a $\times 4$ and/or $\times 8$ package design), the interconnect structure **224** can electrically and mechanically couple the first signal trace **202** of the first redistribution structure **200a** to the third signal trace **216** of the second redistribution structure **200b**. In the illustrated embodiment, the interconnect structure **224** is positioned between the first interconnect pad **208** of the first redistribution structure **200a** and the third interconnect pad **220** of the second redistribution structure **200b**, thereby electrically coupling the first signal trace **202** to the third signal trace **216**. As a result, signals from the first die contact **206** of the first semiconductor die and/or the second die contact **218** of the second semiconductor die are both transmitted to the first package contact **210**.

(30) In the illustrated embodiments of FIG. 2A, there is no interconnect structure between the second interconnect pad **212** of the first redistribution structure **200a** and the fourth interconnect pad **222** of the second redistribution structure **200b**, such that the second signal trace **204** of the first redistribution structure **200a** remains electrically isolated from the third signal trace **216** of the second redistribution structure **200b**. Accordingly, signals from the second die contact **218** of the second semiconductor die are not transmitted to the second package contact **214**. In some embodiments, the second package contact **214** also does not receive any signals from the first semiconductor die because the second signal trace **204** is not connected to any die contacts on the first semiconductor die. As a result, the first package contact **210** can transmit signals from the first and/or second semiconductor dies, while the second package contact **214** remains unused.

(31) Referring to FIG. 2B, in a second package design (e.g., a $\times 16$ package design), the

interconnect structure **224** can electrically and mechanically couple the second signal trace **204** of the first redistribution structure **200a** to the third signal trace **216** of the second redistribution structure **200b**. In the illustrated embodiment, the interconnect structure **224** is positioned between the second interconnect pad **212** of the first redistribution structure **200a** and the fourth interconnect pad **222** of the second redistribution structure **200b**, thereby electrically coupling the second signal trace **204** to the third signal trace **216**. As a result, signals from the second die contact **218** of the second semiconductor die can be transmitted to the second package contact **214**. In some embodiments, the second package contact **214** does not receive any signals from the first semiconductor die because the second signal trace **204** is not connected to any die contacts on the first semiconductor die.

(32) In the illustrated embodiments of FIG. 2B, there is no interconnect structure between the first interconnect pad **208** of the first redistribution structure **200a** and the third interconnect pad **220** of the second redistribution structure **200b**, such that the first signal trace **202** of the first redistribution structure **200a** remains electrically isolated from the third signal trace **216** of the second redistribution structure **200b**. As a result, the first package contact **210** can receive signals from the first die contact **206** but not the second die contact **218**. In such embodiments, the first package contact **210** can transmit signals from the first semiconductor die while the second package contact **214** can transmit signals from the second semiconductor die.

(33) The first and second redistribution structures **200a-b** can be configured in many different ways to achieve the package-dependent signal routing described herein. For example, although in FIGS. 2A and 2B the first interconnect pad **208** is between the first die contact **206** and the first package contact **210**, in other embodiments the first die contact **206** can be between the first interconnect pad **208** and the first package contact **210**. As another example, the locations of the first signal trace **202** and the second signal trace **204** can be interchanged, such that the first interconnect pad **208** of the first redistribution structure **200a** is aligned with the fourth interconnect pad **222** of the second redistribution structure **200b**, and the second interconnect pad **212** of the first redistribution structure **200a** is aligned with the third interconnect pad **220** of the second redistribution structure **200b**. Optionally, the first die contact **206** can be omitted and/or the second signal trace **204** can be electrically coupled to a die contact. In some embodiments, the first redistribution structure **200a** includes additional signal traces (e.g., one, two, three, four, five, or more additional signal traces) each having a corresponding interconnect pad, and the second redistribution structure **200b** can include a corresponding number of interconnect pads to allow the third signal trace **216** to be selectively connected to the additional signal traces based on the positioning of the interconnect structure **224**.

(34) FIGS. 3A and 3B illustrate a first semiconductor die **102a** and a second semiconductor die **102b** configured in accordance with embodiments of the present technology. More specifically, FIG. 3A is a top view of the upper surface **106a** of the first semiconductor die **102a** and FIG. 3B is a top view of the lower surface **108b** of the second semiconductor die **102b**. As previously described, the first and second semiconductor dies **102a-b** can be arranged in a F2F configuration in which the lower surface **108b** of the second semiconductor die **102b** is aligned with and positioned over the upper surface **106a** of the first semiconductor die **102a**. The first semiconductor die **102a** includes a first redistribution structure **300a** formed on the upper surface **106a** and the second semiconductor die **102b** includes a second redistribution structure **300b** formed on the lower surface **108b**. The first and second redistribution structures **300a-b** can be generally similar to the corresponding structures previously described with respect to FIGS. 1-2B.

(35) Referring to FIG. 3A, for example, the first redistribution structure **300a** can include signal traces **302a**, die contacts **304a**, interconnect pads **306a**, and package contacts **308**. As can be seen in FIG. 3A, some signal traces **302a** are connected to a respective die contact **304a**, interconnect pad **306a**, and package contact **308** (e.g., signal trace **312**), while other signal traces **302a** are connected to a respective interconnect pad **306a** and package contact **308** but not to any of the die

contacts **304a** (e.g., signal trace **314**). The signal traces **302a** can be spaced apart and/or electrically isolated from each other so that signal transmission can occur independently along each signal trace **302a**.

(36) In the illustrated embodiment, the die contacts **304a** are arranged in a single row along or near the central axis of the first semiconductor die **102a**, and the interconnect pads **306a** are arranged in multiple rows surrounding both sides of the row of die contacts **304a**. The package contacts **308** can be arranged in two rows extending respectively along two of the lateral edges of the first semiconductor die **102a**. Accordingly, the signal traces **302a** can extend outwardly in two directions from the central portion of the semiconductor die to the peripheral portions to route signals from the die contacts **304a** and/or interconnect pads **306a** to the package contacts **308**. In other embodiments, the first redistribution structure **300a** can be configured differently (e.g., the die contacts **304a** can be arranged in two or more rows, the package contacts **308** can be arranged in a single row along a single lateral edge of the first semiconductor die **102a**, the interconnect pads **306a** can be arranged in fewer or more rows, the interconnect pads **306a** can be located on a single side of the row of die contacts **304a**, etc.).

(37) Referring to FIG. 3B, the second redistribution structure **300b** can include signal traces **302b**, die contacts **304b**, and interconnect pads **306b**. As can be seen in FIG. 3B, each signal trace **302b** can be connected to a corresponding die contact **304b** and at least two interconnect pads **306b**. The signal traces **302b** can be spaced apart and/or electrically isolated from each other so that signals can be transmitted independently along each signal trace **302b**. In the illustrated embodiment, the second redistribution structure **300b** does not include any package contacts for directly connecting to a package substrate. In other embodiments, however, the second redistribution structure **300b** can include one or more package contacts for directly connecting to the package substrate.

(38) In the illustrated embodiment, the die contacts **304b** are arranged in a single row along or near the central axis of the second semiconductor die **102b**, and the interconnect pads **306b** are arranged in multiple rows surrounding both sides of the row of die contacts **304b**. In other embodiments, the second redistribution structure **300b** can be configured differently (e.g., the die contacts **304b** can be arranged in two or more rows, the interconnect pads **306b** can be arranged in fewer or more rows, the interconnect pads **306b** can be located on a single side of the row of die contacts **304b**, etc.).

(39) The signal routing between the first and second semiconductor dies **102a-b** via the first and second redistribution structures **300a-b** can be switched or otherwise varied based on the positioning of interconnect structures (e.g., solder balls) between the first and second semiconductor dies **102a-b**, as previously described with respect to FIGS. 2A and 2B. In some embodiments, the arrangement of the interconnect pads **306a** of the first semiconductor die **102a** can be identical or generally similar to the arrangement of the interconnect pads **306b** of the second semiconductor die **102b**. Thus, the first and second redistribution structures **300a-b** can be bridged by interconnect structures positioned between interconnect pads **306a-b**, as previously described.

(40) Optionally, the interconnect pads **306a** of the first redistribution structure **300a** can be arranged in pairs (or larger groupings) to allow for switchable signal routing between the corresponding pairs of signal traces **302a**, and the interconnect pads **306b** of the second redistribution structure **300b** can be arranged in corresponding pairs (or larger groupings) to align with the pairs of the first redistribution structure **300a**. For example, a pair of interconnect pads **310a** ("pair **310a**") of the first redistribution structure **300a** can be aligned with a corresponding pair of interconnect pads **310b** ("pair **310b**") of the second redistribution structure **300b** to allow for switchable signal routing through a pair of signal traces **312**, **314** of the first semiconductor die **102a**.

(41) FIGS. 4A and 4B illustrate signal routing through the first and second semiconductor dies **102a-b** of FIGS. 3A and 3B, respectively, in a first package design (e.g., a $\times 4$ and/or $\times 8$ package design) configured in accordance with embodiments of the present technology. In the illustrated

embodiment, some of the interconnect pads **306a-b** are connected by interconnect structures (not shown) (“Connected”), while other interconnect pads **306a-b** are not connected by any interconnect structures (“Not connected”). Depending on the arrangement of the interconnect structures, each signal trace **302a** and package contact **308** can either: (1) receive signals from the first semiconductor die **102a** and not the second semiconductor die **102b** (“Die 1”), (2) receive signals from the second semiconductor die **102b** and not the first semiconductor die **102a** (“Die 2”), (3) receive signals either from the first and/or second semiconductor dies **102a-b** (“Die 1 and/or Die 2”), or (4) not receive signals from either the first or second semiconductor dies **102a-b** (“none”). (42) For example, in the illustrated embodiment, a first interconnect pad **316a** of pair **310a** is connected to a second interconnect pad **316b** of pair **310b** by an interconnect structure (not shown), while the remaining interconnect pads of pairs **310a-b** are not connected to each other. As a result, signals from die contact **318a** of the first semiconductor die **102a** and/or die contact **318b** of the second semiconductor die **102** can both be transmitted to package contact **320** via signal trace **312**, while signal trace **314** and package contact **322** remain unused and do not receive signals from either the first or second semiconductor dies **102a-b**.

(43) FIGS. 5A and 5B illustrate signal routing through the first and second semiconductor dies **102a-b** of FIGS. 3A and 3B, respectively, in a second package design (e.g., a $\times 16$ package design) configured in accordance with embodiments of the present technology. In the second package design, the locations of some or all the interconnect structures (not shown) can be different from the locations in the first package design. As a result, the signal routing for some or all of the signal traces **302a** and package contacts **308** can be different from the routing in the first package design. For example, signal traces **302a** and package contacts **308** that previously received signals from both the first and second semiconductor dies **102a-b** can now receive signals from the first semiconductor die **102a** only or the second semiconductor die **102b** only; signal traces **302a** and package contacts **308** that were previously unused can now receive signals from the first and/or second semiconductor dies **102a-b**; and so on.

(44) For example, in the illustrated embodiment, a second interconnect pad **317a** of pair **310a** is connected to a second interconnect pad **317b** of pair **310b** by an interconnect structure (not shown), while the remaining pairs interconnect pads of pairs **310a-b** are not connected to each other. As a result, signal trace **312** and package contact **320** receive signals from die contact **318a** of the first semiconductor die **102a**, while signal trace **314** and package contact **322** receive signals from the die contact **318b** of the second semiconductor die **102b**.

(45) The present technology can provide switchable routing of many different types of signals used in semiconductor packages, such as data signals, control signals, address signals, calibration signals, or any other signal type known to those of skill in the art. The connectivity and configuration of the signals can be varied as desired in a package-dependent manner in accordance with the techniques described herein.

(46) FIGS. 6A-6D illustrate signal routing through a package substrate **103** configured in accordance with embodiments of the present technology. More specifically, FIG. 6A is a top view of a first routing layer **600a** of the package substrate **103**, FIG. 6B is a top view of a second routing layer **600b** of the package substrate **103**, FIG. 6C is a top view of a third routing layer **600c** of the package substrate **103**, and FIG. 6D is a top view of the package substrate **103** with the routing layers **600a-c** overlaid onto each other. The package substrate **103** can be incorporated in any embodiment of the semiconductor packages described herein (e.g., package **100** of FIG. 1).

(47) The first routing layer **600a** of the package substrate **103** can be electrically coupled to the lower surface of a first semiconductor die **102a** (the outline of the first semiconductor die **102a** is shown in FIGS. 6A-6D merely to illustrate the positioning relative to the package substrate **103**). The second routing layer **600b** can be electrically coupled to an array of electrical connectors **124** (e.g., a ball grid array—FIGS. 6B and 6D include outlines of the electrical connectors **124** merely to illustrate the positioning relative to the package substrate **103**). As previously described with

respect to FIG. 1, the electrical connectors **124** can be used to electrically couple the package substrate **103** to external devices or other higher-level components to allow signals to be transmitted thereto. In some embodiments, the package substrate **103** is electrically coupled to the first semiconductor die **102a** via wires (not shown). The wires can connect package contacts (not shown) on the first semiconductor die **102a** to corresponding bond pads **118** included in or electrically coupled to the first routing layer **600a** of the package substrate **103**. Each bond pad **118** can be electrically coupled to a corresponding electrical connector **124** via wiring, traces, metal layers or structures, vias, or other electrically conductive features extending along and/or through the routing layers **600a-c** of the package substrate **103**.

(48) In some embodiments, the number and/or positioning of the bond pads **118** relative to the electrical connectors **124** can make it difficult or impossible to route all of the electrical interconnections between the bond pads **118** and electrical connectors **124** in a single layer of the package substrate **103**. For example, the locations of the bond pads **118** may be constrained by the geometry of the first semiconductor die **102a**. Signal routing through the package substrate **103** can become more congested and challenging as the width of the first semiconductor die **102a** approaches the width of the array of electrical connectors **124**. To ameliorate these issues, the package substrate **103** can route the electrical interconnections between the bond pads **118** and electrical connectors **124** over multiple layers (e.g., at least two, three, four, or more layers). For example, a first subset of signals from the bond pads **118** can be routed through the first routing layer **600a** ("1st subset"), a second subset of signals can be routed through the second routing layer **600b** ("2nd subset"), a third subset of signals can be routed through the third routing layer **600c** ("3rd subset"), and so on.

(49) In the illustrated embodiment, for example, the bond pads **118** include a first subset of bond pads **610**, a second subset of bond pads **620**, and, optionally, a third subset of bond pads **630** (reference numbers are shown only for a single example of each subset merely for purposes of clarity). In some embodiments, the first bond pads **610** correspond to a first set of data signals for the semiconductor package (e.g., the upper byte), the second bond pads **620** correspond to a second set of data signals (e.g., the lower byte), and the third bond pads **630** correspond to other signals (e.g., control signals, address signals, calibration signals, power signals, etc.). Each subset of the bond pads **118** can be electrically coupled to a corresponding subset of the array of electrical connectors **124** via respective wiring structures. For example, the first bond pads **610** can connect to a first subset of electrical connectors **612** via first wiring structures **614**, the second bond pads **620** can connect to a second subset of electrical connectors **622** via second wiring structures **624**, and, optionally, the third subset of bond pads **630** can connect to a third subset of electrical connectors **632** via wiring structures **634**.

(50) The signals from the first bond pads **610** can be routed in the first routing layer **600a**. Accordingly, as shown in FIG. 6A, the first wiring structures **614** can be located in the first routing layer **600a**, and can extend from the first bond pads **610** to respective first vias **616**. In some embodiments, the first bond pads **610** are located at or near the peripheral portion of the package substrate **103**, while the first vias **616** are located away from the first bond pads **610** at or near the interior portion of the package substrate **103**. The first vias **616** can be located near the first electrical connectors **612** to provide electrical connections thereto. As shown in FIGS. 6A and 6B, for example, each of the first vias **616** can extend through the first routing layer **600a** to a location in the second routing layer **600b** adjacent or near the corresponding first electrical connector **612**.

(51) The signals from the second bond pads **620** can be routed in the second routing layer **600b**, rather than in the first routing layer **600a**. Accordingly, as shown in FIG. 6A, in the first routing layer **600a**, the second bond pads **620** can be connected to respective second vias **626** that are located near the second bond pads **620** (e.g., near the peripheral portions of the package substrate **103**). As shown in FIGS. 6A and 6B, the second vias **626** can extend through the first routing layer **600a** to a location in the second routing layer **600b** away from the corresponding second electrical

connectors **622**. The second wiring structures **624** can be located in the second routing layer **600b** and can extend from the second vias **626** to the second electrical connectors **622**.

(52) Referring to FIGS. **6C** together, the package substrate **103** can optionally include a third routing layer **600c** between the first and second routing layers **600a-b**. In such embodiments, the first vias **616** and second vias **626** can extend through the routing layer **600c**. The third routing layer **600c** can also be used for routing signals from the third bond pads **630**. Accordingly, as shown in FIG. **6A**, in the first routing layer **600a**, the third bond pads **630** can be connected to third vias **626a** that are located near the third bond pads **630** (e.g., near the peripheral portions of the package substrate **103**). As shown in FIGS. **6A** and **6C**, the third vias **636** can extend through the first routing layer **600a** and into the third routing layer **600c**. The third wiring structures **634** can be located in the third routing layer **600c** and can extend from the third vias **636** to fourth vias **638**. The fourth vias **638** can be spaced apart from the third vias **636**. As shown in FIGS. **6B** and **6C**, the fourth vias **638** can extend through the third routing layer **600c** to a location in the second routing layer **600b** adjacent or near the corresponding third electrical connectors **632**.

(53) FIG. **6D** shows the package substrate **103** with the routing layers **600a-c** overlaid onto each other. As can be seen from the illustrated embodiment, the use of multiple routing layers as described herein allows for numerous and complex interconnections between the bond pads **118** and the electrical connectors **124**. In other embodiments, the package substrate **103** can include fewer or more routing layers (e.g., one, two, four, five, or more routing layers) each including respective wiring structures for routing signals between subsets of the bond pads **118** and the electrical connectors **124**. The package substrate **103** can also include additional layers not shown in FIGS. **6A-6D**. For example, the package substrate **103** can include one or more layers of insulating material between routing layers to reduce or prevent electrical interference. The package substrate **103** can also include one or more layers of material configured to provide structural support and/or mechanical strength.

(54) Any one of the semiconductor devices and/or packages having the features described above with reference to FIGS. **1-6D** can be incorporated into any of a myriad of larger and/or more complex systems, a representative example of which is system **700** shown schematically in FIG. **7**. The system **700** can include a processor **702**, a memory **704** (e.g., SRAM, DRAM, flash, and/or other memory devices), input/output devices **706**, and/or other subsystems or components **708**. The semiconductor dies and/or packages described above with reference to FIGS. **1-6D** can be included in any of the elements shown in FIG. **7**. The resulting system **700** can be configured to perform any of a wide variety of suitable computing, processing, storage, sensing, imaging, and/or other functions. Accordingly, representative examples of the system **700** include, without limitation, computers and/or other data processors, such as desktop computers, laptop computers, Internet appliances, hand-held devices (e.g., palm-top computers, wearable computers, cellular or mobile phones, personal digital assistants, music players, etc.), tablets, multi-processor systems, processor-based or programmable consumer electronics, network computers, and minicomputers. Additional representative examples of the system **700** include lights, cameras, vehicles, etc. With regard to these and other example, the system **700** can be housed in a single unit or distributed over multiple interconnected units, e.g., through a communication network. The components of the system **700** can accordingly include local and/or remote memory storage devices and any of a wide variety of suitable computer-readable media.

(55) From the foregoing, it will be appreciated that specific embodiments of the technology have been described herein for purposes of illustration, but that various modifications may be made without deviating from the disclosure. Accordingly, the invention is not limited except as by the appended claims. Furthermore, certain aspects of the new technology described in the context of particular embodiments may also be combined or eliminated in other embodiments. Moreover, although advantages associated with certain embodiments of the new technology have been described in the context of those embodiments, other embodiments may also exhibit such

advantages and not all embodiments need necessarily exhibit such advantages to fall within the scope of the technology. Accordingly, the disclosure and associated technology can encompass other embodiments not expressly shown or described herein.

Claims

1. A method of manufacturing a semiconductor package, the method comprising: forming a first redistribution structure on a first semiconductor die; forming a second redistribution structure on a second semiconductor die; and selecting, based on a design of the semiconductor package, either a first position or a second position for an interconnect structure between the first and second semiconductor dies, wherein: the first position corresponds to the interconnect structure electrically coupling a contact of the second die through the first and second redistribution structures to a first package contact of the semiconductor package, and the second position corresponds to the interconnect structure electrically coupling the contact of the second die through the first and second redistribution structures to a second package contact of the semiconductor package; and electrically coupling the first and second semiconductor dies with the interconnect structure in the selected first or second position.
2. The method of claim 1 wherein the design is a $\times 4$ and/or a $\times 8$ package design and the method further comprises positioning the interconnect structure in the first position such that a contact of the first die is also electrically coupled to the first package contact.
3. The method of claim 2, further comprising transmitting a signal from one or more of the contact of the first die and the contact of the second die to the first package contact.
4. The method of claim 1 wherein the design is a $\times 16$ package design and the method further comprises positioning the interconnect structure in the second position such that a contact of the first die contact is electrically coupled to the first package contact and the contact of the second die is electrically coupled to the second package contact.
5. The method of claim 4, further comprising: transmitting a first signal from the contact of the first die to the first package contact; and transmitting a second signal from the contact of the second die to the second package contact, wherein the second signal is different from the first signal.
6. The method of claim 1, further comprising: mounting the first semiconductor die on a package substrate; and mounting the second semiconductor die on the first semiconductor die.
7. The method of claim 6 wherein the first and second semiconductor dies are mounted in a face-to-face configuration.
8. The method of claim 6, further comprising wirebonding the first semiconductor die to the package substrate.
9. A method of manufacturing a semiconductor package, the method comprising: mounting a first semiconductor die to a package substrate, the first semiconductor die including: a first interconnect pad electrically coupled to both a first die contact of the first semiconductor die and a first package contact, and a second interconnect pad electrically coupled to a second package contact and electrically isolated from the first interconnect pad; and mounting a second semiconductor die to the first semiconductor die, the second semiconductor die including: a third interconnect pad and a fourth interconnect pad, both electrically coupled to a second die contact of the second semiconductor die, wherein either (1) the first interconnect pad is coupled to the third interconnect pad by a first interconnect structure to configure the semiconductor package for a first package configuration while the second interconnect pad is electrically isolated from the fourth interconnect pad, or (2) the second interconnect pad is coupled to the fourth interconnect pad by a second interconnect structure to configure the semiconductor package for a second package configuration while the first interconnect pad is electrically isolated from the third interconnect pad.
10. The method of claim 9 wherein the first package configuration has half as many data channels as the second package configuration.

11. The method of claim 9 wherein the first package configuration is a $\times 4$ and/or a $\times 8$ configuration and the second package configuration is a $\times 16$ configuration.
 12. The method of claim 9 wherein either the first interconnect structure or the second interconnect structure is comprised by a redistribution layer disposed between the first semiconductor die and the second semiconductor die.
 13. A method of manufacturing a semiconductor package comprising: mounting a first semiconductor die to a package substrate, the first semiconductor die including: a first interconnect pad electrically coupled to both a first die contact of the first semiconductor die and a first package contact, and a second interconnect pad electrically coupled to a second package contact and electrically isolated from the first interconnect pad; and mounting a second semiconductor die to the first semiconductor die, the second semiconductor die including: a third interconnect pad and a fourth interconnect pad, both electrically coupled to a second die contact of the second semiconductor die, wherein (1) the first interconnect pad is vertically aligned with the third interconnect pad, and (2) the second interconnect pad is vertically aligned with the fourth interconnect pad, and wherein either (1) the first interconnect pad is coupled to the third interconnect pad by a first interconnect structure while the second interconnect pad is electrically isolated from the fourth interconnect pad, or (2) the second interconnect pad is coupled to the fourth interconnect pad by a second interconnect structure while the first interconnect pad is electrically isolated from the third interconnect pad.
 14. The method of claim 13, wherein the first interconnect structure electrically couples the first interconnect pad to the third interconnect pad such that the first and second die contacts are both electrically coupled to the first package contact.
 15. The method of claim 14 wherein the first interconnect structure is a solder bump.
 16. The method of claim 13, wherein the second interconnect structure electrically couples the second interconnect pad to the fourth interconnect such that the first die contact is electrically coupled to the first package contact and the second die contact is electrically coupled to the second package contact.
 17. The method of claim 16 wherein the second interconnect structure is a solder bump.
 18. The method of claim 13 wherein: the first die contact, the first interconnect pad, and the second interconnect pad are at an interior portion of the first semiconductor die; the first and second package contacts are at a peripheral portion of the first semiconductor die; and the second die contact, the third interconnect pad, and the fourth interconnect pad are at an interior portion of the second semiconductor die.
 19. The method of claim 13 wherein the first and second package contacts are electrically coupled to respective first and second bond pads on the package substrate via wire bonds.
 20. The method of claim 19 wherein the package substrate is coupled to a first electrical connector and a second electrical connector, the first electrical connector is electrically coupled to the first bond pad, and the second electrical connector is electrically coupled to the second bond pad.
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